

Description

Features

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low RDS(ON)

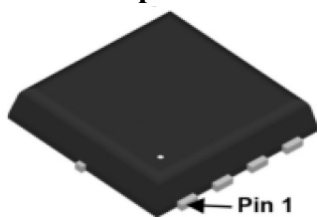
Application

- High current load application
- Load switching
- Quick Charge

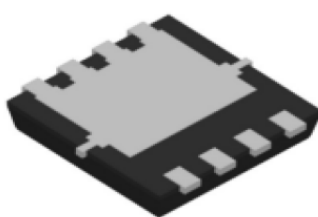
V_{DS}	-30	V
$R_{ds(on),typ}@V_{gs}=-10V$	7.3	m Ω
$R_{ds(on),typ}@V_{gs}=-4.5V$	11	m Ω
I_D	-47	A



Top View

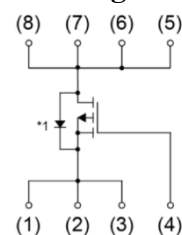


Bottom View



PDFN3.3*3.3 Pin Configuration

- (1) Source
 - (2) Source
 - (3) Source
 - (4) Gate
 - (5) Drain
 - (6) Drain
 - (7) Drain
 - (8) Drain
- *1 Body Diode



Package Marking and Ordering Information

Part	Marking	Package	Packing	Reel Size	Tape Width	Qty
CMT30P47K	T30P47K	PDFN3.3*3.3	Reel	NA	NA	5000pcs

Key Performance Parameters

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS}=-10V^1$	-47	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS}=-10V^1$	-35	A
IDM	Pulsed Drain Current ²	-160	A
EAS	Single Pulse Avalanche Energy ⁵	160	mJ
$PD@T_c=25^\circ C$	Total Power Dissipation ³	43	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_j	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ	Max	Units
R _{θJA}	Thermal Resistance Junction-Ambient ¹	68	75	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	2.6	2.9	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
BVDSS	Drain-Source Breakdown Voltage	-30	--	--	V	VGS=0V, ID=-250uA
RDS(ON)	Static Drain-Source On-Resistance ²	--	7.3	9	mΩ	VGS=-10V, ID=-20A
		--	11	13		VGS=-4.5V, ID=-10A
VGS(th)	Gate Threshold Voltage	-2	-1.6	-1.2	V	VGS=VDS, ID=-250uA
IDSS	Drain-Source Leakage Current	--	--	-1	uA	VDS=-30V, VGS=0V, TJ=25°C
		--	--	-30	uA	VDS=-24V, VGS=0V, TJ=125°C
IGSS	Gate-Source Leakage Current	--	--	±100	nA	VGS=±20V, VDS=0V
gfs	Forward Transconductance	--	13.8	--	Ns	VDS=-10V, ID=-10A
Rg	Gate Resistance	--	15	--	Ω	VDS=0V, VGS=0V, f=1MHz
Qg	Total Gate Charge (10V)	--	45	--	nC	VDS=-15V, VGS=-4.5V, ID=-20A
Qgs	Gate-Source Charge	--	13	--		
Qgd	Gate-Drain Charge	--	15	--		
Td(on)	Turn-On Delay Time	--	24.1	--	ns	VDD=-15V, VGS=-10V, RG=6Ω ID=-20A
Tr	Rise Time	--	10	--		
Td(off)	Turn-Off Delay Time	--	152	--		
Tf	Fall Time	--	48	--		
Ciss	Input Capacitance	--	2659	--	pF	VDS=-15V, VGS=0V, f=1MHz
Coss	Output Capacitance	--	407	--		
Crss	Reverse Transfer Capacitance	--	301	--		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Units
Is	Continuous Source Current ^{1,4}	VG=VD=0V, Force Current	-47	--	A
Ism	Pulsed Source Current ^{2,4}		-160	--	A
VSD	Diode Forward Voltage ²	VGS=0V, IS=-10A, TJ=25°C	-1.2	--	V

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
- 3.The power dissipation is limited by 150°C junction temperature.
- 4.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.
- 5.The EAS data shows Max. rating. The test condition is VDD=-20V, VGS=-10V, L=0.5mH.

Typical Performance Characteristics

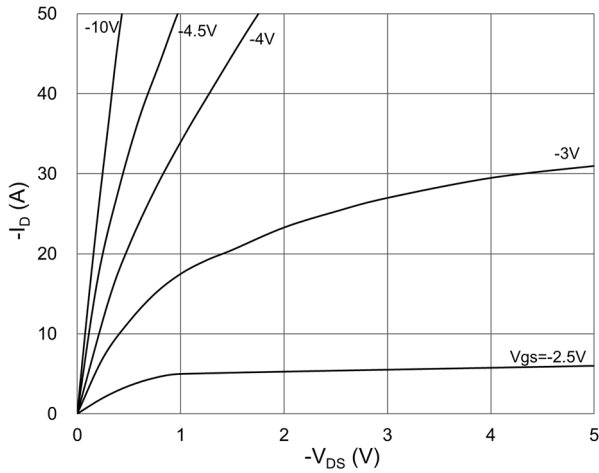
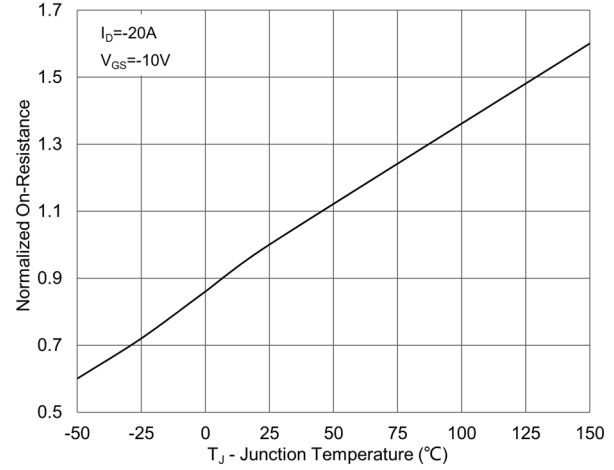
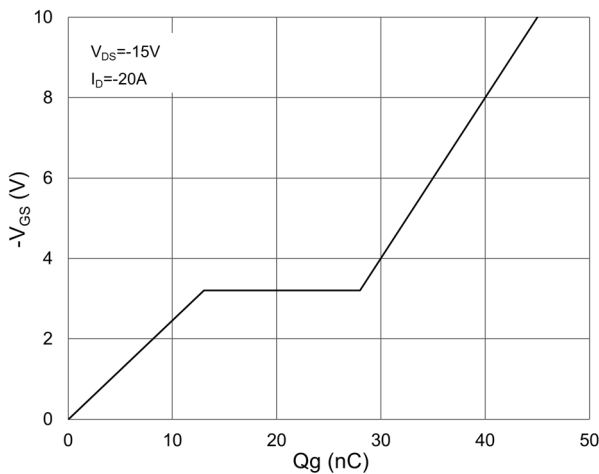
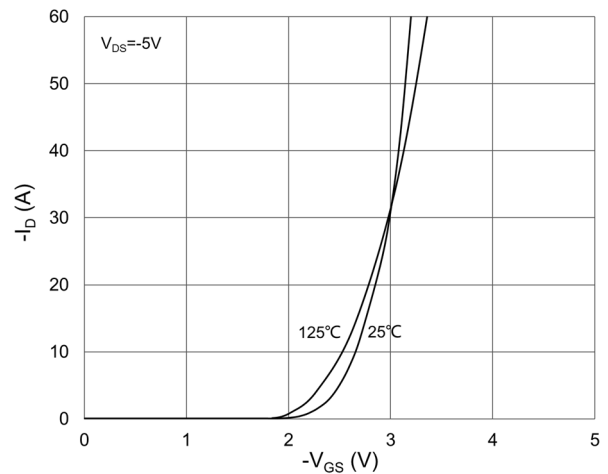
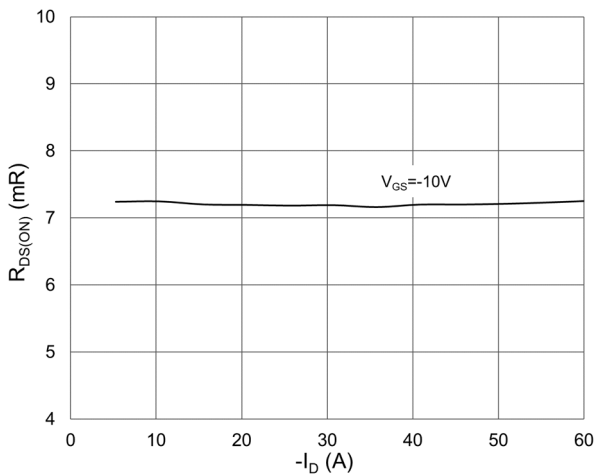
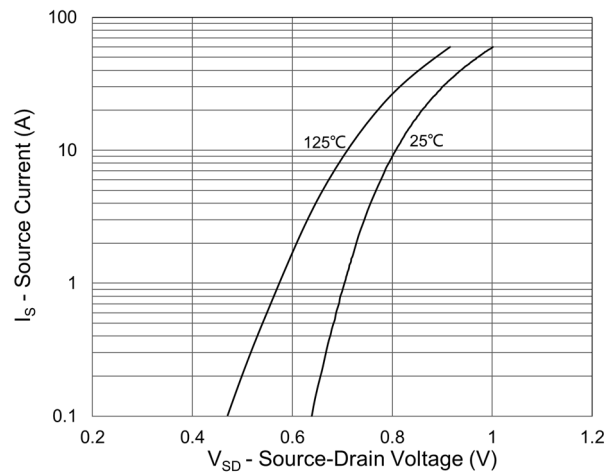
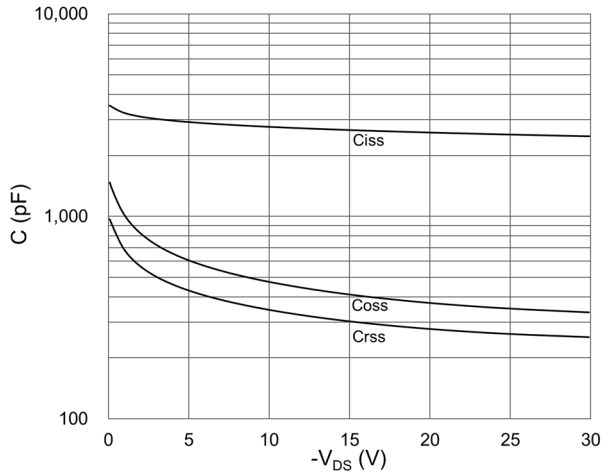
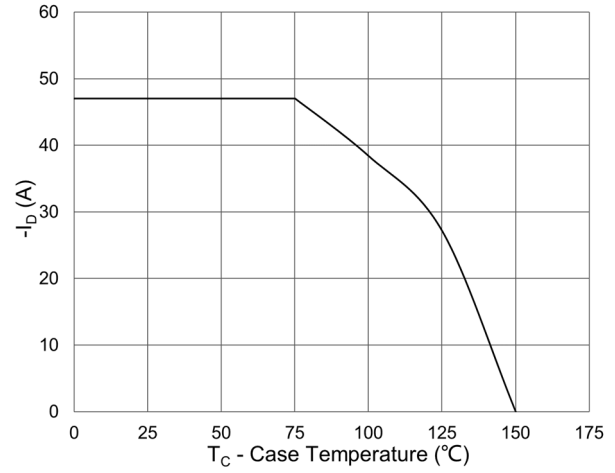
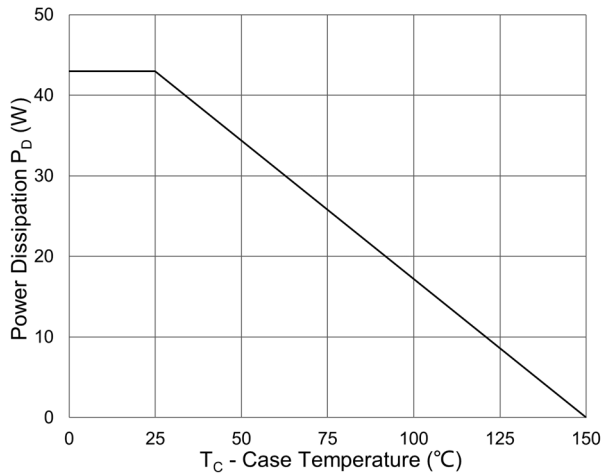
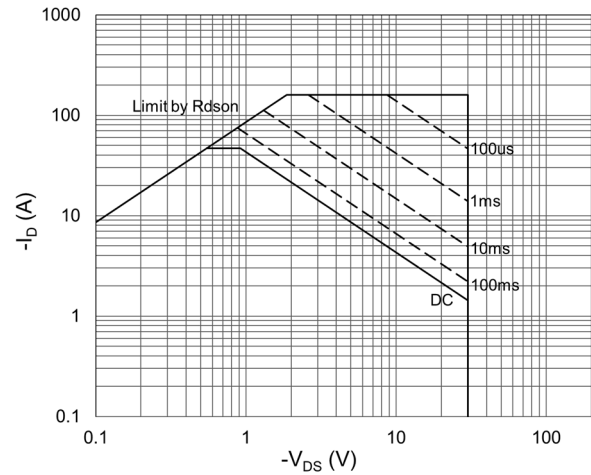
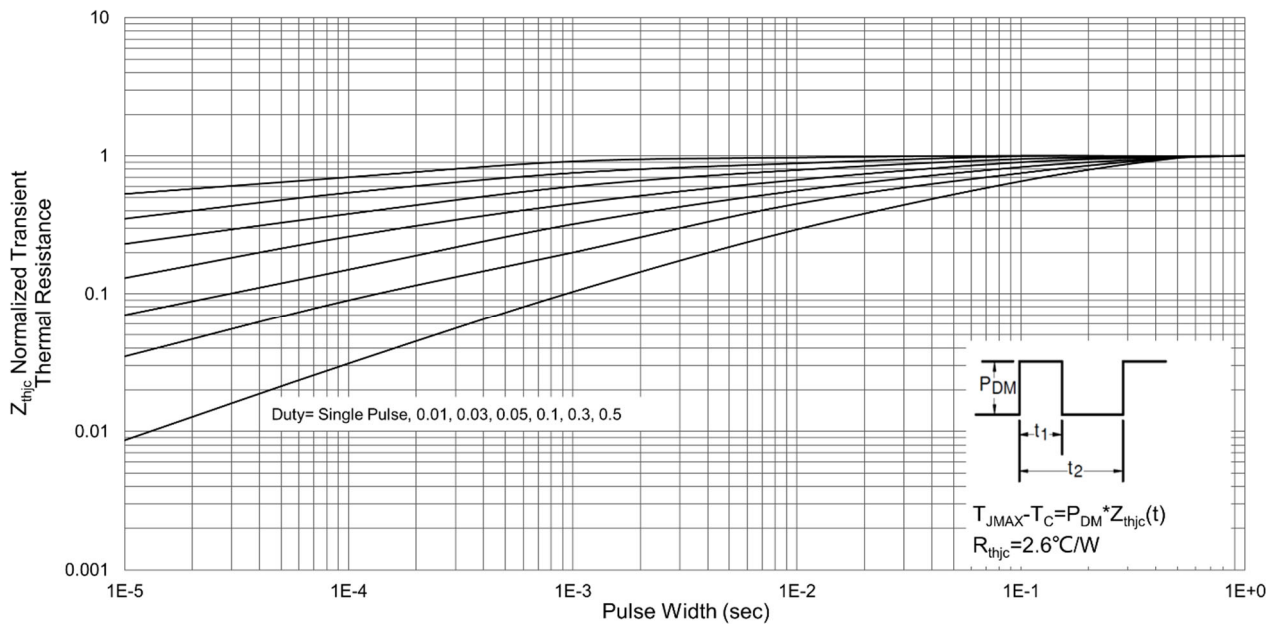
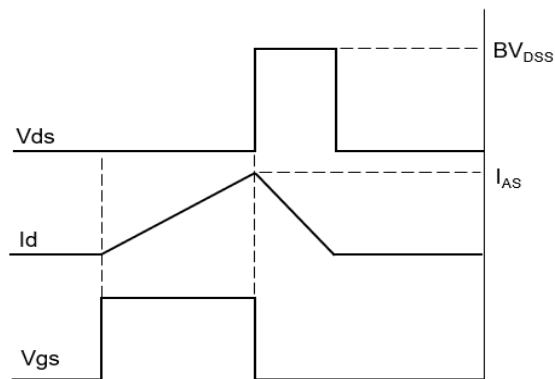
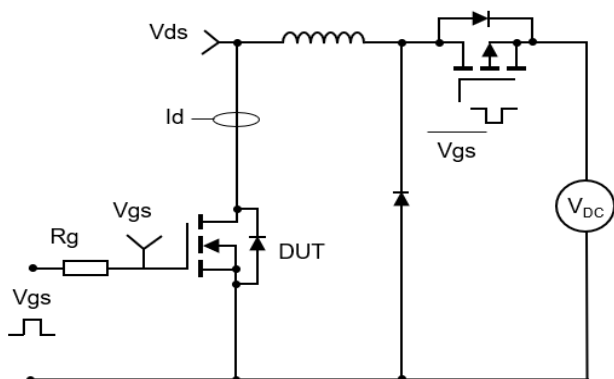
Fig1 Output Characteristics

Fig2 Normalized $R_{DS(on)}$ vs. T_J

Fig3 Gate Charge Waveform

Fig4 Transfer Characteristics

Fig5 $R_{DS(on)}$ vs. Drain Current and Gate Voltage

Fig6 Source-Drain Diode Forward Characteristics


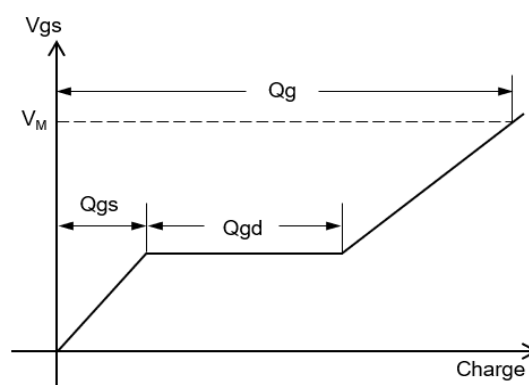
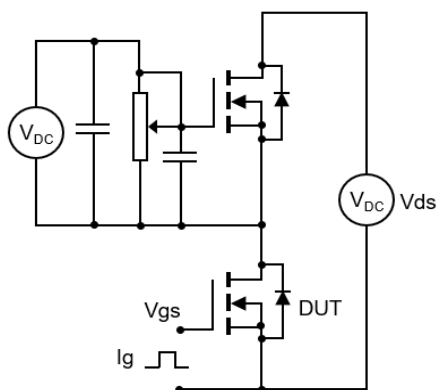
Fig7 Capacitance Characteristics

Fig8 Drain Current Derating

Fig9 Power Dissipation

Fig10 Maximum Safe Operation Area

Fig11 Normalized Transient Impedance


Test Circuit & Waveform

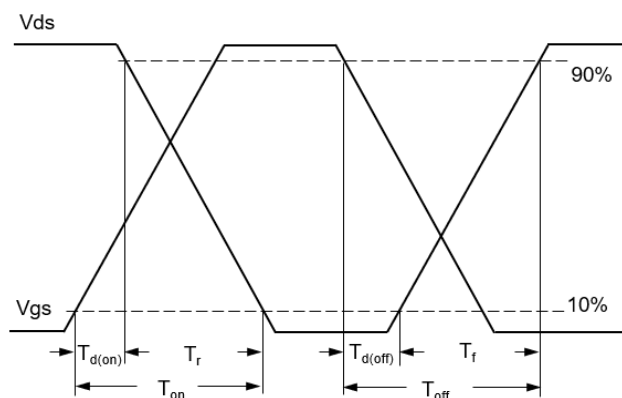
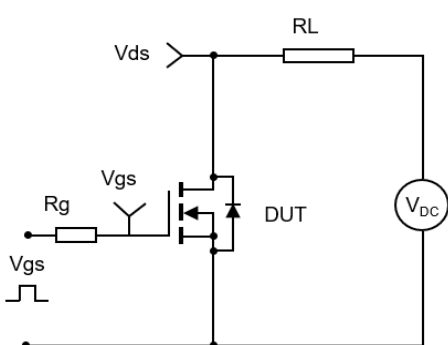
1. Unclamped Inductive Switching Test Circuit & Waveforms



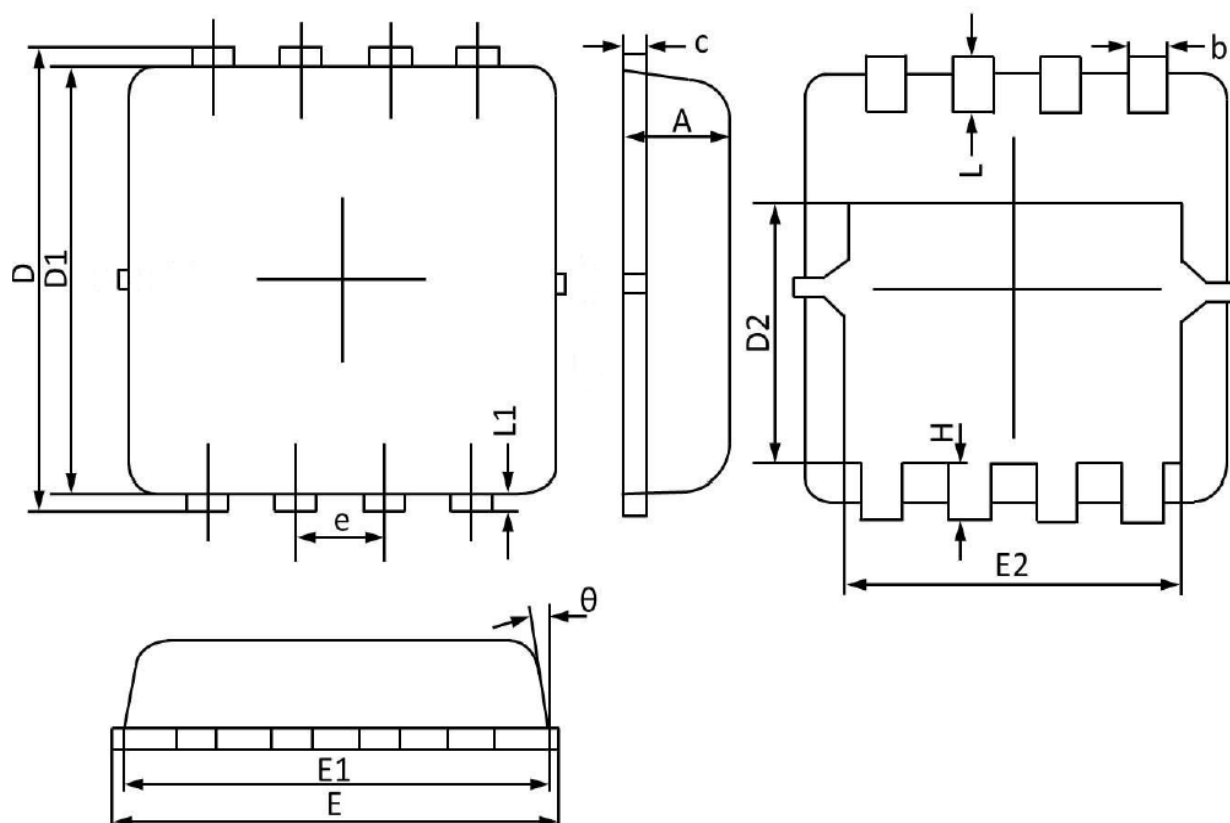
2. Gate Charge Test Circuit & Waveform



3. Resistive Switching Test Circuit & Waveform



PDFN3.3*3.3 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°